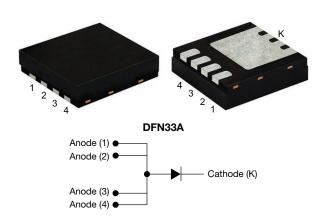


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Vishay General Semiconductor

Surface-Mount TMBS® (Trench MOS Barrier Schottky) Rectifier



LINKS TO ADDITIONAL RESOURCES





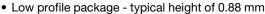






PRIMARY CHARACTERISTICS				
I _{F(AV)}	9 A			
V_{RRM}	150 V			
I _{FSM}	150 A			
V_F at $I_F = 4.5$ A $(T_J = 125 ^{\circ}C)$	0.56 V			
T _J max.	175 °C			
Package	DFN33A			
Circuit configuration	Single			

FEATURES





• Leadless DFN package with side-wettable flanks suitable for customer AOI (Automatic Optical Inspection)



COMPLIANT HALOGEN

FREE

Very low voltage drop by TMBS Gen3

- technology
- · Low power losses, high efficiency
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
 - Automotive ordering code; base P/NHM3
- · Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

TYPICAL APPLICATIONS

For use in low voltage, high frequency inverters, freewheeling, DC/DC converters, and polarity protection applications.

MECHANICAL DATA

Case: DFN33A

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant, and

commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and

AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	V9N3M153	UNIT	
Device marking code		9M153		
Maximum repetitive peak reverse voltage	V _{RRM}	150	V	
Maximum average forward rectified current (fig. 1)	I _{F(AV)} (1)	I _{F(AV)} ⁽¹⁾ 9		
Maximum average forward rectified current (fig. 1)	I _{F(AV)} (2)	2.4	А	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	150	А	
Operating junction temperature range	T _J ⁽³⁾	-40 to +175	°C	
Storage temperature range	T _{STG}	-55 to +175	°C	

Notes

- (1) With infinite heatsink
- (2) Free air, mounted on FR4 PCB, 2 oz., standard footprint
- (3) The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta,JA}$



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ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise noted)								
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT		
Instantaneous forward voltage	I _F = 4.5 A	T _J = 25 °C	V _F ⁽¹⁾	0.70	-	V		
	I _F = 9 A			0.85	1.00			
	$I_F = 4.5 A$	- T _J = 125 °C		0.56	=			
	I _F = 9 A			0.64	0.69			
Reverse current	V - 100 V	T _J = 25 °C T _J = 125 °C	I _R ⁽²⁾	1 (2)	1_ (2)	0.0014	=	mA
	v _R = 100 v	T _J = 125 °C		1.2	-	IIIA		
	$V_R = 150 \text{ V}$ $T_J = 25$ $T_J = 12$	T _J = 25 °C	I _R ⁽²⁾	-	0.1	- mA		
		T _J = 125 °C		3	8			
Typical junction capacitance	4.0 V, 1 MHz		CJ	510	-	pF		

Notes

⁽²⁾ Pulse test: pulse width ≤ 5 ms

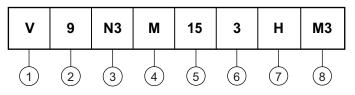
THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise specified)				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
	R _{0JA} (1)(2)	118	148	°C/W
Thermal resistance	R ₀ JA (3)	-	65	
	R _{0JM} (4)	2.9	3.63	

Notes

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
- (2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint
- (3) Thermal resistance junction-to-ambient, free air with device mounted on FR4 PCB, 2 oz., 20 mm x 20 mm pad area
- (4) Thermal resistance junction-to-mount to follow JEDEC 51-14 transient dual interface test method (TDIM)

ORDERING INFORMATION TABLE





- 1 Vishay TMBS product
- 2 Current rating (9 = 9 A)
- Package type (N3 = DFN33A)
- Process type option (M = low I_R)
- 5 Voltage rating (15 = 150 V)
- TMBS generation option (3 = Gen3)
- Quality grade (H = AEC-Q101 qualified, otherwise = industry grade)
- Material / environmental category (M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free)

ORDERING INFORMATION (Example)					
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE	
V9N3M153-M3/I	0.031	I	6000	13" diameter plastic tape and reel	
V9N3M153HM3/I (1)	0.031	I	6000	13" diameter plastic tape and reel	

Note

(1) AEC-Q101 qualified

⁽¹⁾ Pulse test: 300 µs pulse width, 1 % duty cycle

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RATINGS AND CHARACTERISTICS CURVES ($T_A = 25$ °C unless otherwise noted)

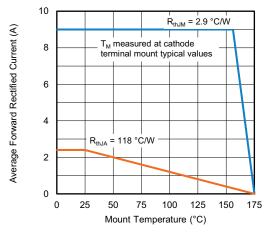


Fig. 1 - Maximum Forward Current Derating Curve

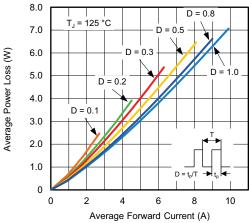


Fig. 2 - Forward Power Loss Characteristics

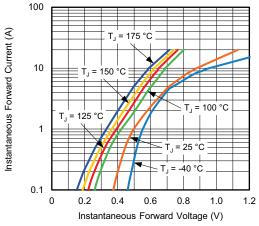


Fig. 3 - Typical Instantaneous Forward Characteristics

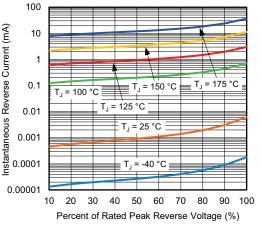


Fig. 4 - Typical Reverse Characteristics

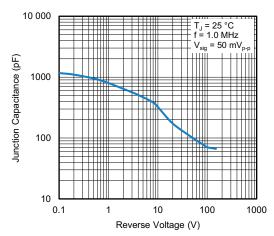


Fig. 5 - Typical Junction Capacitance

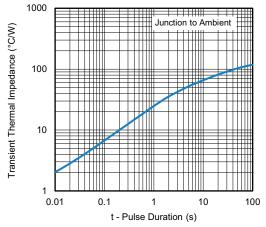


Fig. 6 - Typical Transient Thermal Impedance



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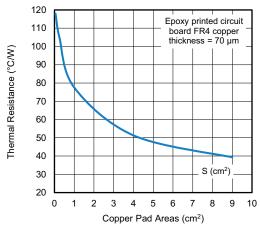
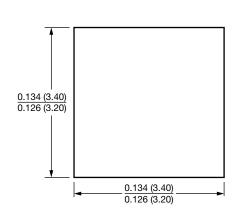
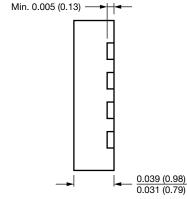


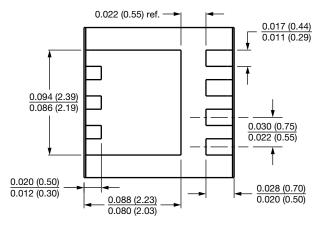
Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

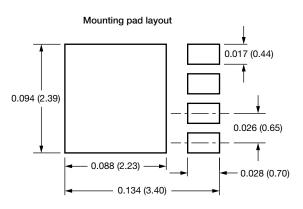
PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

DFN33A Mir











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Vishay

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